RoodMicrotec
powerful solutions

RoodMicrotec Newsletter

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Expansion of authorised capital to enhance resources

On 12 December we announced that we wished to expand our authorised capital.

In view of the current large number of promising projects and anticipating on the probability of success of a considerable number of these, we must be able to take decisive action. Of course, we cannot negotiate with the handbrake on.
When a customer believes a project has great potential, he wants to be certain that the partners he works with are able to participate and grow.
We can provide that certainty by expanding our authorised capital, in order to be able to move quickly.

Expanding of our authorised capital may also be needed in case of a strategic acquisition. We have decided not to postpone this decision until the next AGM.

Furthermore, we are still working to strengthen the organisation so as to fully exploit the opportunities that are now before us.
We have recently been joined by two high-quality employees:
Dipl.-Ing (FH) Walter Schock as our new *Automotive Competence Centre Manager* and Dr.-Ing. Joachim Kusterer who will work on *RoodMicrotec's eXtended Supply Chain Service*.

We are looking forward to fleshing out these positive developments further in 2015.

I wish all our employees, shareholders and other stakeholders a merry Christmas and a positive and successful New Year.

Automotive Competence Centre


Walter Schock

Demand from our customers to support them in supplying the automotive industry is increasing.

This demand is coming from Asia as well as from European customers, largely from Fabless Companies. We are delighted to announce Mr Dipl.-Ing (FH) Walter Schock has joined us as our new Automotive Competence Centre Manager . He has many years' experience as senior supplier engineer working in the automotive industry for an OEM and Tier1 supplier.
He will be able to channel the needs of our customers to supply their designs and services to them in a professional way to high level end-customers.


Joachim Kusterer

Introducing Dr.-Ing. Joachim Kusterer

In October, Dr.-Ing. Joachim Kusterer joined. He studied Electrical Engineering at and received his PhD from the University of Ulm (Germany).

After obtaining his Master's degree in the field of microelectronics, he worked as research engineer with GFD, a start-up company located at the DaimlerChrysler Research & Development Center in Ulm. Back at the University of Ulm after 2 years, he worked as a PhD student and researcher on sensors and actuators for harsh environments and extreme conditions.
Based on diamond and GaN technologies Joachim developed amongst other things RF MEMS, biosystems, chemical sensors, paper quality detectors and FETs. He published a number of articles in scientific magazines, one book chapter and a review paper as leading author, one book chapter as co-author, and gave numerous presentations at international conferences. At the Diamond 2006 in Estoril he was awarded the prize for best poster presentation.

His expertise covers the development chain for electronic devices and systems starting from finite-element-analysis and mask design to process development and wafer fabrication to system integration and test. Apart from technological issues he also has a great deal of experience of patent issues and proposal preparation for public funding.

Joachim will work on RoodMicrotec's Supply Chain Service to help make it a leading global player in the field of semiconductor devices and systems. He will coordinate technical details in the eXtended supply chain with suppliers on system design, wafer fabrication, wafer testing (in-house), chip packaging, System-in-Package assembly, qualification and final device tests, board assembly and final system tests.

RoodMicrotec presents its services at the Electronica fair in Munich

From 11 November to 14 November Rood Microtec presented its services at the 2014 Electronica trade fair in Munich, which had its 50th anniversary this year.

The Electronica, the leading trade fair for components, systems and applications in electronics, has again set standards in the international arena.

Visitors were able to get a very good impression of RoodMicrotec's competence from our various professional lectures about failure analysis at the well placed booth in hall 5. Customers had a chance to chat to our qualified staff available throughout the fair.

On the first day of the fair, the COG Germany (Components Obsolescence Group) hosted its 2nd Obsolescence Day, where the visitors could get advice about Obsolescence Management at our booth. Methods and services to minimize negative effects of the obsolescence of components were presented.

On Thursday evening we invited our customers to a get-together at our booth, leading to interesting conversations in a relaxed atmosphere with some tasty nibbles and wine.

With more than 73.000 professional visitors from more than 80 countries and 2,737 exhibitors, the 2014 Electronica fair was well attended this year, and it was a great success for RoodMicrotec. We are delighted with the number of new contacts and good conversations with customers during the fair and we expect a positive impact on our business.

Successful RoodMicrotec Seminar on 'Failures of Printed Circuit Assemblies and Their Prevention' in October 2014

On October 16th, RoodMicrotec's 3rd seminar took place in Stuttgart.

Almost 100 participants from the industry and research institutes joined this year's in-depth training on recognition and prevention of printed circuit assembly failures.

Areas covered included manufacturing process problems, necessary layout design rules and their origin as well as environmental influences.

Theoretical knowledge and directly applicable practical expertise for designers as well as for quality related personnel were provided in twelve talks throughout the day.
According to the participants, the opportunity to exchange experiences and views on the most recent developments of the electronics industry was a further key factor for their visit.

'I would recommend the seminar especially to all designers,' said a PCB designer from the automotive industry.

Another seminar is planned for the autumn of 2015 to continue the successful knowledge transfer.
A few interested people have already marked the date of our next seminar in their diaries.

Several projects to enter test engineering phase

This year, we have been working on an unprecedented number of projects.
These are projects in the Industrial and Automotive, Hi-Rel/Space and Smart Grid markets, which are very important for us.

In Industrial, we have various customers in (oil) mining, in which electrical devices are used that can withstand temperatures of up to +2250 C.
In Automotive it mainly concerns electrical devices in the head unit, the display that contains all the infotainment in cars. This is a strongly growing market, in which leading car brands are among our clientèle.
In Hi-Rel/Space we are involved in a number of projects for image sensors in various applications and LEDs for communication in satellites.
The home smart grid market focuses on devices used to set temperatures, switch ovens, lights and washing machines on and off, including energy control. In this market we are also working on a number of projects.

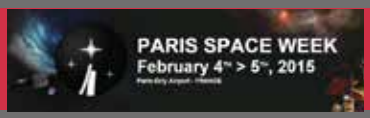
Any projects breaks up into several different stages. It starts with design. Once all the data for the integrated circuit are ready, they are sent to the foundry to make a wafer. This is called the tape-out, and it is a major milestone in the rest of the planning.
Normally speaking, test engineering starts about two months after the tape-out, followed by qualification, which in some cases can take a very long time, for example in the Hi-rel/Space market due to the extreme quality requirements.

The projects we are currently working on, are at various stages of the process.
On one of the projects, the tape-out will be at the end of this year, and we will be able to start test engineering in February 2015; on other projects we expect starting mass production in the second half of next year.

What all these projects have in common, is that the quality requirements are very high, and that they will provide recurring sales.

With these projects, our new strategy is taking shape ever more clearly.


Reinhard Pusch

TEC THE EVERTIQ CONFERENCE MUNICH JAN 27 2015	15 January 2015	TEC Munich, the Evertiq Conference	Table-Top exhibition
	4 - 5 February 2015	Space Week in Paris	Table-Top exhibition
embeddedworld2015 Exhibition&Conference	24 - 26 Feburary 2015	Embedded world Nürnberg	Exhibition, hall 4 stand 580
Semicon China Shanghai New International Expo	17 -19 March 2015	Semicon China in Shanghai	Company Community contribution to the official participation of the Federal Republic of Germany

Colophon

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